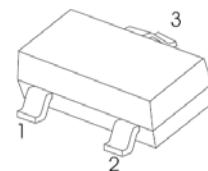


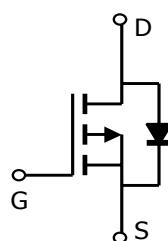
## ■ Features

- $V_{DS} (V) = -30V$
- $I_D = -4.2 A$
- $R_{DS(ON)} < 52m\Omega$  ( $V_{GS} = -10V$ )
- $R_{DS(ON)} < 70m\Omega$  ( $V_{GS} = -4.5V$ )

SOT - 23



1. GATE
2. SOURCE
3. DRAIN

■ Absolute Maximum Ratings  $T_a = 25^\circ C$ 

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current $T_a = 25^\circ C$	$I_D$	-4.2	A
$T_a = 70^\circ C$		-3.5	
Pulsed Drain Current	$I_{DM}$	-20	
Power Dissipation $T_a = 25^\circ C$	$P_D$	1.4	W
$T_a = 70^\circ C$		1	
Thermal Resistance.Junction- to-Ambient $t \leq 10s$	$R_{thJA}$	90	$^\circ C/W$
Steady State		125	
Thermal Resistance.Junction- to-Lead	$R_{thJL}$	60	
Junction Temperature	$T_J$	150	$^\circ C$
Storage Temperature Range	$T_{stg}$	-55 to 150	

## P-Channel Enhancement MOSFET

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	I <sub>D</sub> =-250 μ A, V <sub>GS</sub> =0V	-30			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>D</sub> =-24V, V <sub>GS</sub> =0V			-1	μ A
		V <sub>D</sub> =-24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C			-5	
Gate-Body leakage current	I <sub>GSS</sub>	V <sub>D</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>D</sub> =V <sub>GS</sub> I <sub>D</sub> =-250 μ A	-1	-1.8	-3	V
Static Drain-Source On-Resistance	R <sub>Ds on</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-4.1A			52	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A			70	
On state drain current	I <sub>D(on)</sub>	V <sub>GS</sub> =-4.5V, V <sub>D</sub> =-5V	-10			A
Forward Transconductance	g <sub>FS</sub>	V <sub>D</sub> =-5V, I <sub>D</sub> =-4A	5.5	8.2		S
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>D</sub> =-15V, f=1MHz		700		pF
Output Capacitance	C <sub>oss</sub>			120		
Reverse Transfer Capacitance	C <sub>rss</sub>			75		
Gate resistance	R <sub>g</sub>	V <sub>GS</sub> =0V, V <sub>D</sub> =0V, f=1MHz		10		Ω
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =-4.5V, V <sub>D</sub> =-15V, I <sub>D</sub> =-4A		14.3		nC
Gate Source Charge	Q <sub>gs</sub>			7		
Gate Drain Charge	Q <sub>gd</sub>			3.1		
Turn-On DelayTime	t <sub>d(on)</sub>	V <sub>GS</sub> =-10V, V <sub>D</sub> =-15V, R <sub>L</sub> =3.6 Ω ,R <sub>GEN</sub> =3 Ω		8.6		ns
Turn-On Rise Time	t <sub>r</sub>			5		
Turn-Off DelayTime	t <sub>d(off)</sub>			28.2		
Turn-Off Fall Time	t <sub>f</sub>			13.5		
Body Diode Reverse Recovery Time	t <sub>rr</sub>			27		
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =-4A, dI/dt=100A/ μ s		15		nC
Maximum Body-Diode Continuous Current	I <sub>s</sub>				-2.2	A
Diode Forward Voltage	V <sub>SD</sub>	I <sub>s</sub> =-1A, V <sub>GS</sub> =0V		-0.77	-1	V

### ■ Typical Characteristics

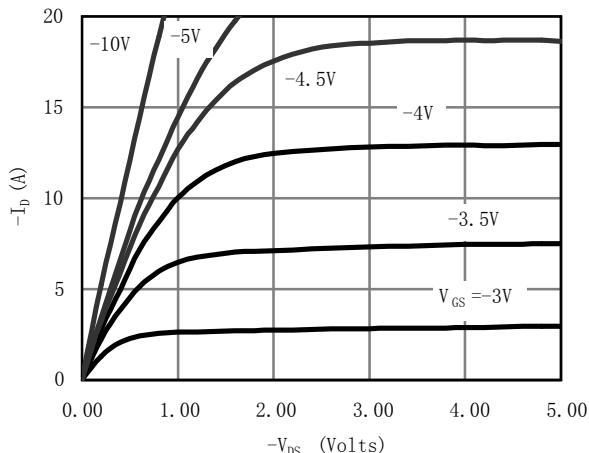


Figure 1: On-Region Characteristics

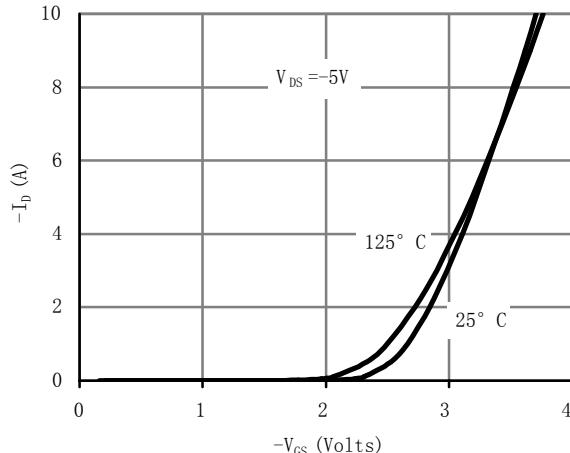


Figure 2: Transfer Characteristics

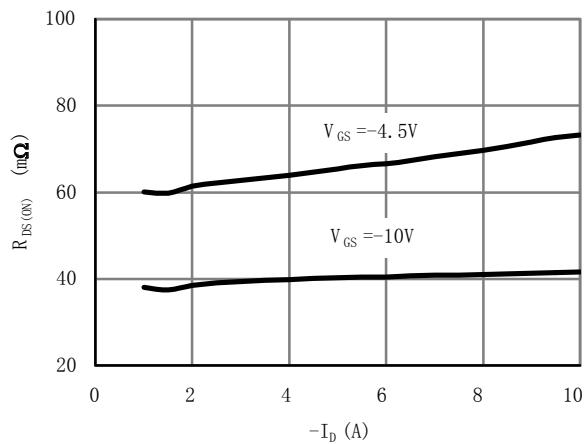


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

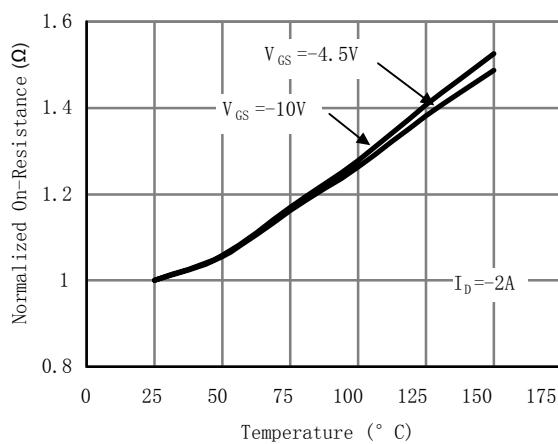


Figure 4: On-Resistance vs. Junction Temperature

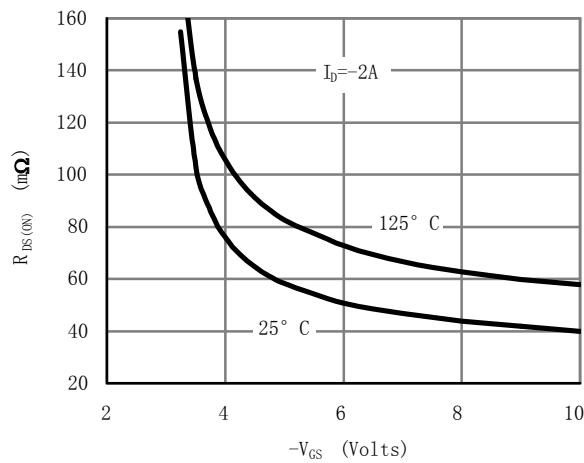


Figure 5: On-Resistance vs. Gate-Source Voltage

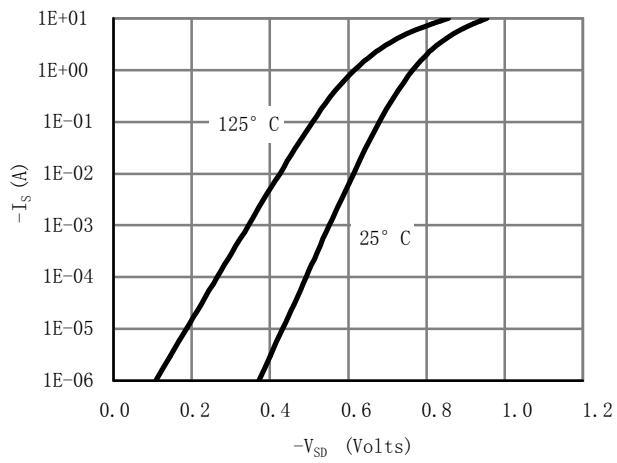
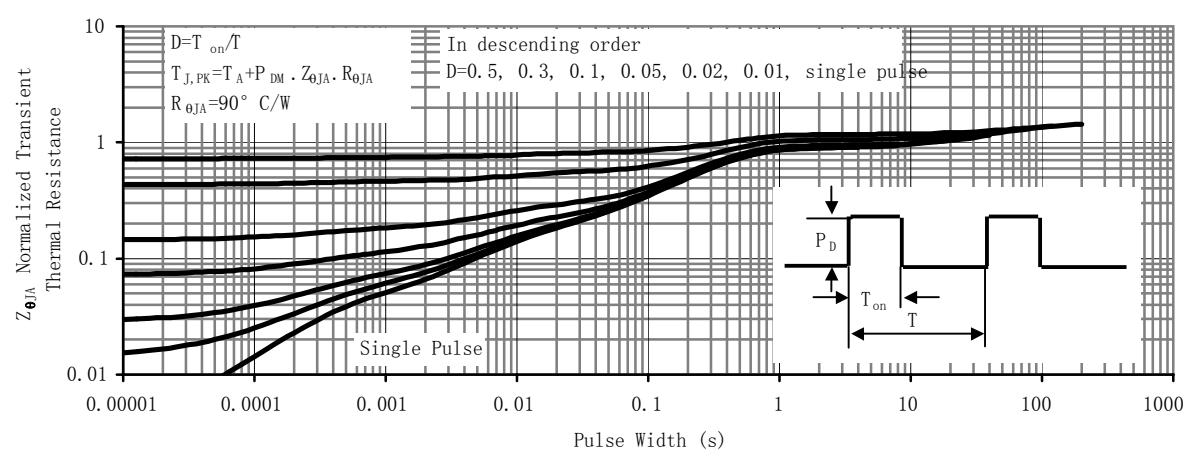
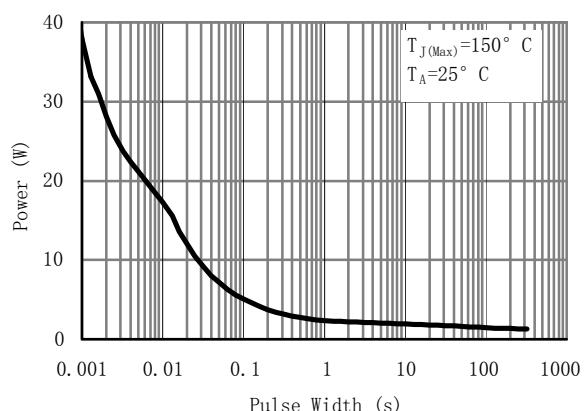
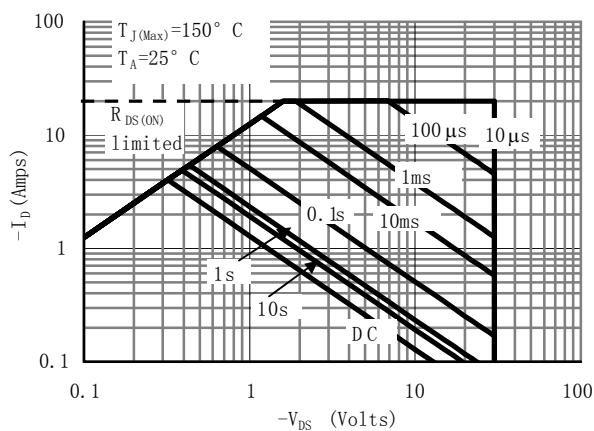
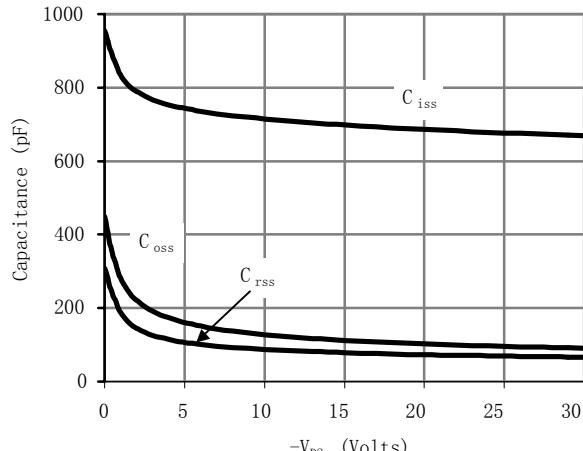
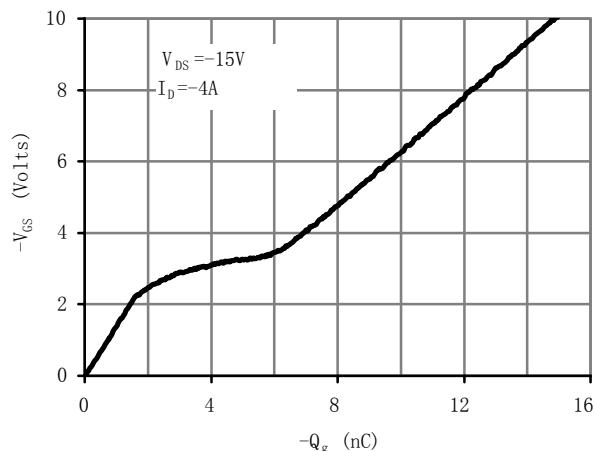
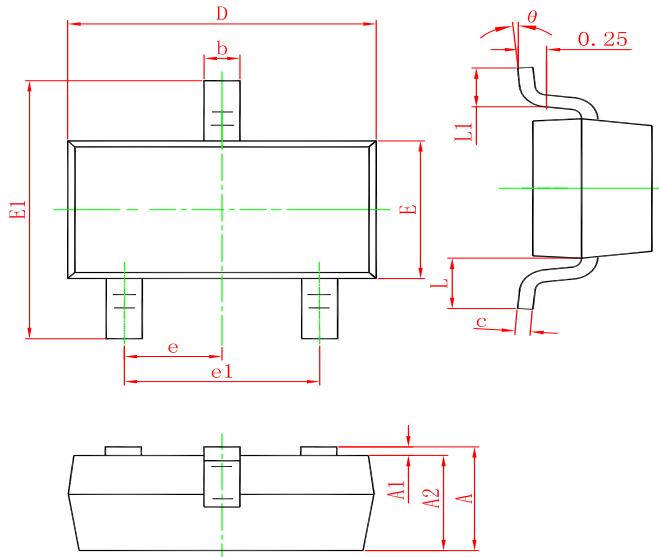


Figure 6: Body-Diode Characteristics

## ■ Typical Characteristics

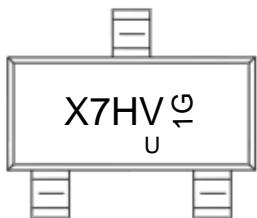


## SOT-23 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

## Marking



## Ordering information

Order code	Package	Baseqty	Delivery mode
AO3407A	SOT-23	3000	Tape and reel